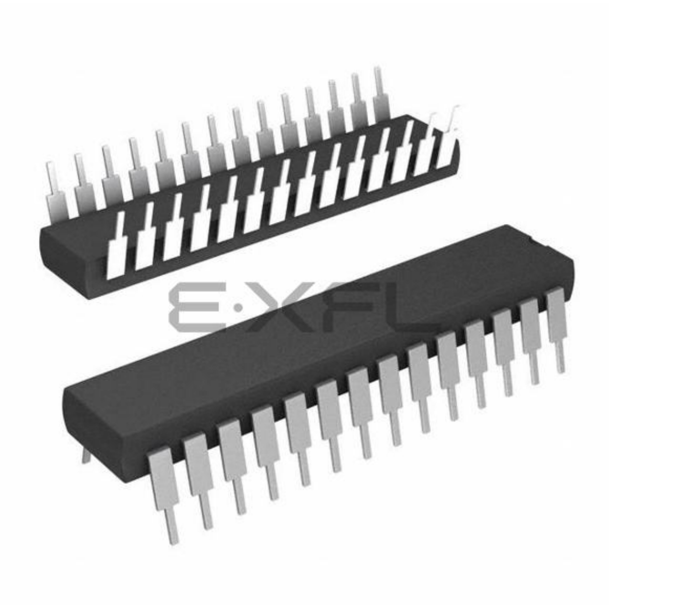

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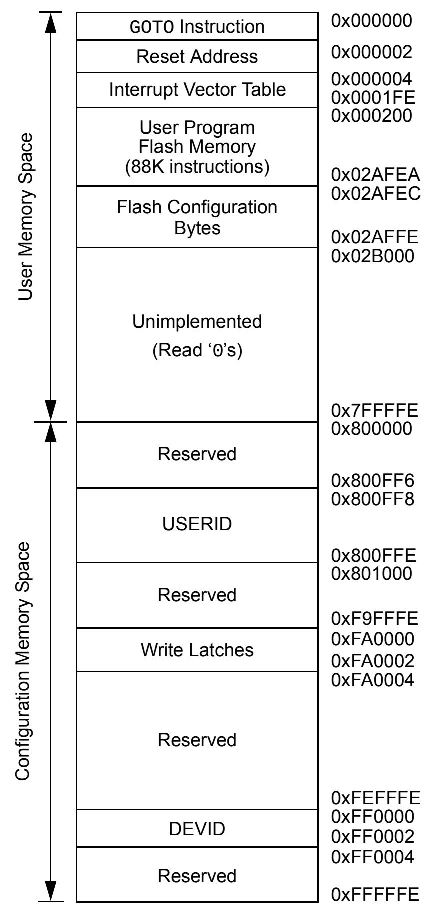
"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	70 MIPs
Connectivity	I²C, IrDA, LINbus, QEI, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, Motor Control PWM, POR, PWM, WDT
Number of I/O	21
Program Memory Size	256KB (85.5K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 16
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 6x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep256mc202-i-sp

FIGURE 4-4: PROGRAM MEMORY MAP FOR dsPIC33EP256GP50X, dsPIC33EP256MC20X/50X AND PIC24EP256GP/MC20X DEVICES



Note: Memory areas are not shown to scale.

4.6 Modulo Addressing (dsPIC33EPXXXMC20X/50X and dsPIC33EPXXXGP50X Devices Only)

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.6.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified, and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-1).

Note:	Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.6.2 W ADDRESS REGISTER SELECTION

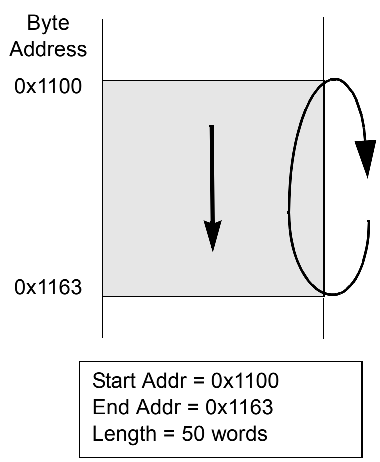
The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

- If XWM = `1111`, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = `1111`, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W register (XWM), to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 4-1). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '`1111`' and the XMODEN bit is set (MODCON<15>).

The Y Address Space Pointer W register (YWM), to which Modulo Addressing is to be applied, is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '`1111`' and the YMODEN bit is set at MODCON<14>.

FIGURE 4-20: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100, W0
MOV     W0, XMODSRT    ;set modulo start address
MOV     #0x1163, W0
MOV     W0, MODEND     ;set modulo end address
MOV     #0x8001, W0
MOV     W0, MODCON     ;enable W1, X AGU for modulo

MOV     #0x0000, W0    ;W0 holds buffer fill value

MOV     #0x1110, W1    ;point W1 to buffer

DO      AGAIN, #0x31   ;fill the 50 buffer locations
MOV     W0, [W1++]     ;fill the next location
AGAIN:  INC W0, W0     ;increment the fill value
```

TABLE 11-2: INPUT PIN SELECTION FOR SELECTABLE INPUT SOURCES (CONTINUED)

Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment	Peripheral Pin Select Input Register Value	Input/ Output	Pin Assignment
010 1000	I/O	RP40	101 0101	—	—
010 1001	I/O	RP41	101 0110	—	—
010 1010	I/O	RP42	101 0111	—	—
010 1011	I/O	RP43	101 1000	—	—
010 1100	I	RPI44	101 1001	—	—
101 1010	—	—	110 1101	—	—
101 1011	—	—	110 1110	—	—
101 1100	—	—	110 1111	—	—
101 1101	—	—	111 0000	—	—
101 1110	I	RPI94	111 0001	—	—
101 1111	I	RPI95	111 0010	—	—
110 0000	I	RPI96	111 0011	—	—
110 0001	I/O	RP97	111 0100	—	—
110 0010	—	—	111 0101	—	—
110 0011	—	—	111 0110	I/O	RP118
110 0100	—	—	111 0111	I	RPI119
110 0101	—	—	111 1000	I/O	RP120
110 0110	—	—	111 1001	I	RPI121
110 0111	—	—	111 1010	—	—
110 1000	—	—	111 1011	—	—
110 1001	—	—	111 1100	—	—
110 1010	—	—	111 1101	—	—
110 1011	—	—	111 1110	—	—
110 1100	—	—	111 1111	—	—

Legend: Shaded rows indicate PPS Input register values that are unimplemented.

Note 1: See **Section 11.4.4.1 "Virtual Connections"** for more information on selecting this pin assignment.

2: These inputs are available on dsPIC33EPXXXGP/MC50X devices only.

REGISTER 11-10: RPINR18: PERIPHERAL PIN SELECT INPUT REGISTER 18

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U1RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **U1RXR<6:0>:** Assign UART1 Receive (U1RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 11-11: RPINR19: PERIPHERAL PIN SELECT INPUT REGISTER 19

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	U2RXR<6:0>						
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-7 **Unimplemented:** Read as ‘0’

bit 6-0 **U2RXR<6:0>:** Assign UART2 Receive (U2RX) to the Corresponding RPn Pin bits (see Table 11-2 for input pin selection numbers)

`1111001` = Input tied to RPI121
.
.
.
`0000001` = Input tied to CMP1
`0000000` = Input tied to VSS

REGISTER 11-26: RPOR8: PERIPHERAL PIN SELECT OUTPUT REGISTER 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP118R<5:0>					
bit 15							bit 8

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as ‘0’

bit 13-8 **RP118R<5:0>:** Peripheral Output Function is Assigned to RP118 Output Pin bits (see Table 11-3 for peripheral function numbers)

bit 7-0 **Unimplemented:** Read as ‘0’

REGISTER 11-27: RPOR9: PERIPHERAL PIN SELECT OUTPUT REGISTER 9

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	RP120R<5:0>					
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-6 **Unimplemented:** Read as ‘0’

bit 5-0 **RP120R<5:0>:** Peripheral Output Function is Assigned to RP120 Output Pin bits (see Table 11-3 for peripheral function numbers)

12.0 TIMER1

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Timers"** (DS70362) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The Timer1 module is a 16-bit timer that can operate as a free-running interval timer/counter.

The Timer1 module has the following unique features over other timers:

- Can be operated in Asynchronous Counter mode from an external clock source
- The external clock input (T1CK) can optionally be synchronized to the internal device clock and the clock synchronization is performed after the prescaler

A block diagram of Timer1 is shown in Figure 12-1.

The Timer1 module can operate in one of the following modes:

- Timer mode
- Gated Timer mode
- Synchronous Counter mode
- Asynchronous Counter mode

In Timer and Gated Timer modes, the input clock is derived from the internal instruction cycle clock (FCY). In Synchronous and Asynchronous Counter modes, the input clock is derived from the external clock input at the T1CK pin.

The Timer modes are determined by the following bits:

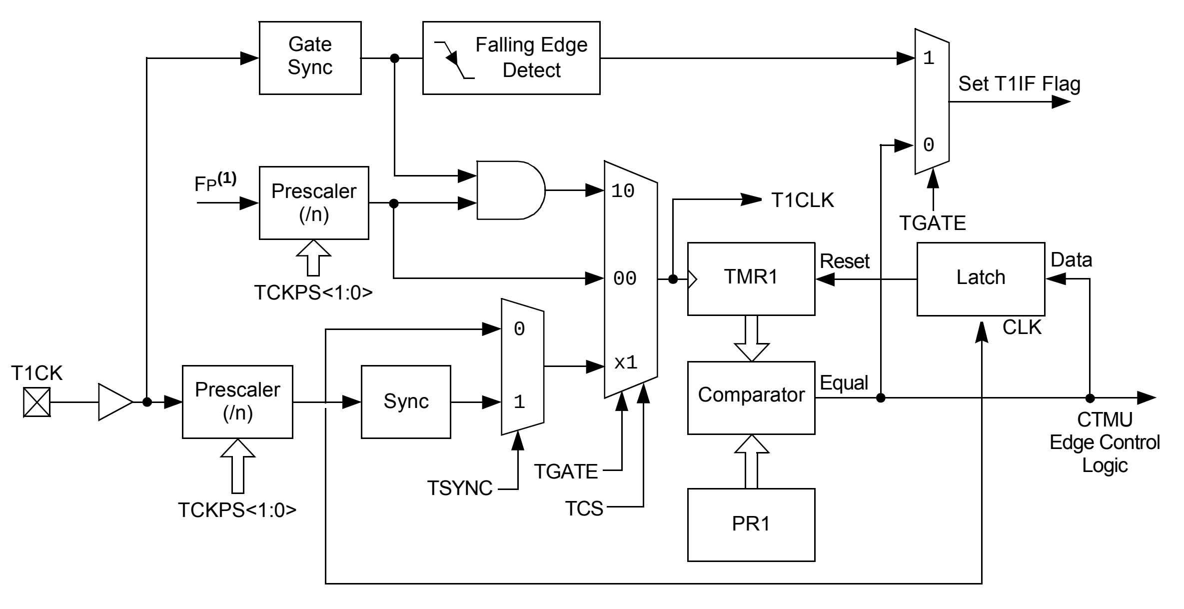
- Timer Clock Source Control bit (TCS): T1CON<1>
- Timer Synchronization Control bit (TSYNC): T1CON<2>
- Timer Gate Control bit (TGATE): T1CON<6>

Timer control bit setting for different operating modes are given in the Table 12-1.

TABLE 12-1: TIMER MODE SETTINGS

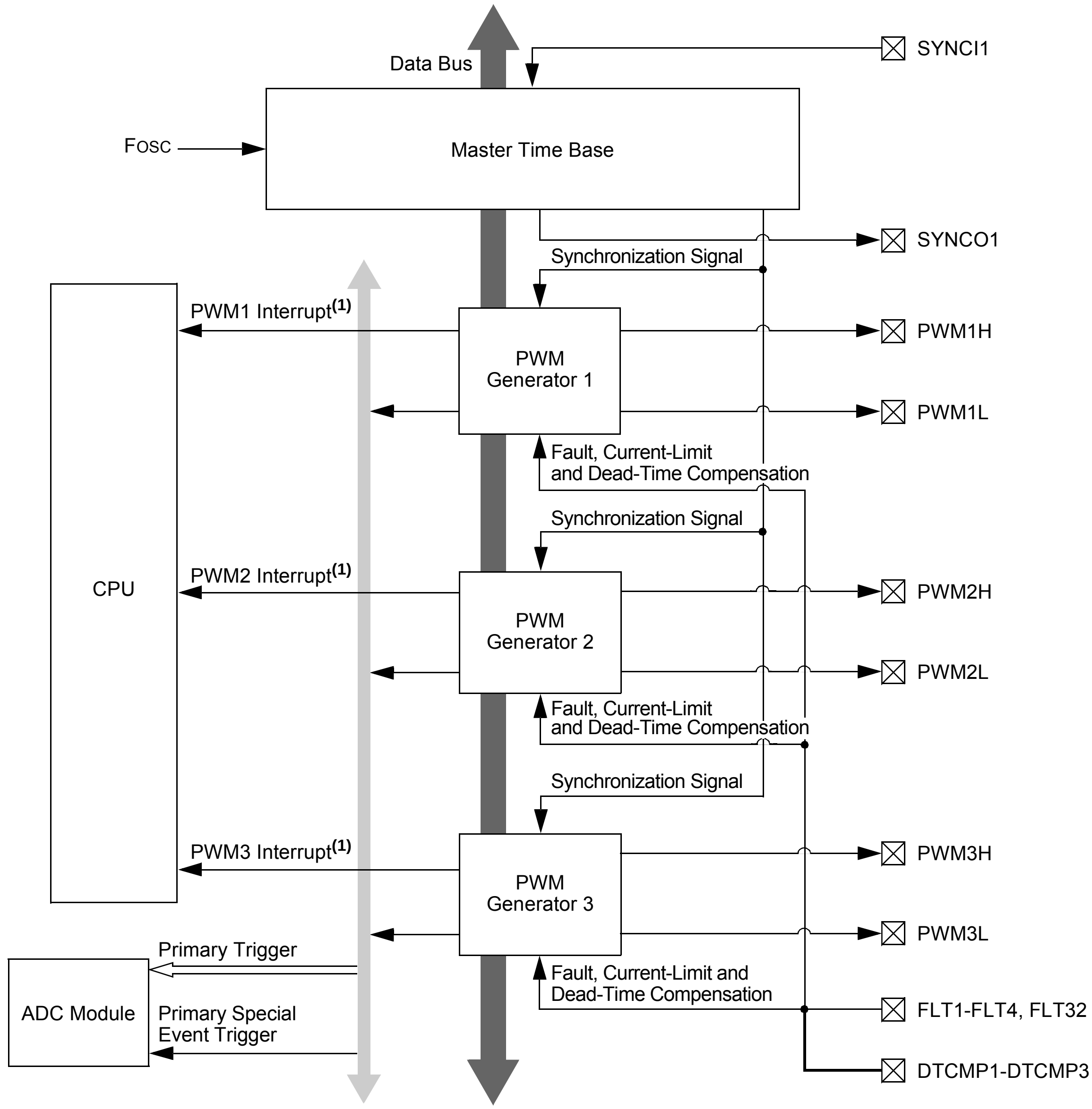
Mode	TCS	TGATE	TSYNC
Timer	0	0	x
Gated Timer	0	1	x
Synchronous Counter	1	x	1
Asynchronous Counter	1	x	0

FIGURE 12-1: 16-BIT TIMER1 MODULE BLOCK DIAGRAM



Note 1: FP is the peripheral clock.

FIGURE 16-1: HIGH-SPEED PWMx MODULE ARCHITECTURAL OVERVIEW



Note 1: The PWM interrupts are generated by logically ORing the FLTSTAT, CLSTAT and TRGSTAT status bits for the given PWM generator. Refer to the "*dsPIC33/PIC24 Family Reference Manual*", **"High-Speed PWM"** (DS70645) for more information.

21.0 ENHANCED CAN (ECAN™) MODULE (dsPIC33EPXXXGP/MC50X DEVICES ONLY)

Note 1: This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Enhanced Controller Area Network (ECAN™)"** (DS70353) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

21.1 Overview

The Enhanced Controller Area Network (ECAN) module is a serial interface, useful for communicating with other CAN modules or microcontroller devices. This interface/protocol was designed to allow communications within noisy environments. The dsPIC33EPXXXGP/MC50X devices contain one ECAN module.

The ECAN module is a communication controller implementing the CAN 2.0 A/B protocol, as defined in the BOSCH CAN specification. The module supports CAN 1.2, CAN 2.0A, CAN 2.0B Passive and CAN 2.0B Active versions of the protocol. The module implementation is a full CAN system. The CAN specification is not covered within this data sheet. The reader can refer to the BOSCH CAN specification for further details.

The ECAN module features are as follows:

- Implementation of the CAN protocol, CAN 1.2, CAN 2.0A and CAN 2.0B
- Standard and extended data frames
- 0-8 bytes data length
- Programmable bit rate up to 1 Mbit/sec
- Automatic response to remote transmission requests
- Up to eight transmit buffers with application specified prioritization and abort capability (each buffer can contain up to 8 bytes of data)
- Up to 32 receive buffers (each buffer can contain up to 8 bytes of data)
- Up to 16 full (Standard/Extended Identifier) acceptance filters
- Three full acceptance filter masks
- DeviceNet™ addressing support
- Programmable wake-up functionality with integrated low-pass filter
- Programmable Loopback mode supports self-test operation
- Signaling via interrupt capabilities for all CAN receiver and transmitter error states
- Programmable clock source
- Programmable link to Input Capture (IC2) module for time-stamping and network synchronization
- Low-power Sleep and Idle mode

The CAN bus module consists of a protocol engine and message buffering/control. The CAN protocol engine handles all functions for receiving and transmitting messages on the CAN bus. Messages are transmitted by first loading the appropriate data registers. Status and errors can be checked by reading the appropriate registers. Any message detected on the CAN bus is checked for errors and then matched against filters to see if it should be received and stored in one of the receive registers.

REGISTER 21-4: CxFCTRL: ECANx FIFO CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	U-0	U-0
DMABS2	DMABS1	DMABS0	—	—	—	—	—
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	FSA4	FSA3	FSA2	FSA1	FSA0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **DMABS<2:0>:** DMA Buffer Size bits

111 = Reserved
110 = 32 buffers in RAM
101 = 24 buffers in RAM
100 = 16 buffers in RAM
011 = 12 buffers in RAM
010 = 8 buffers in RAM
001 = 6 buffers in RAM
000 = 4 buffers in RAM

bit 12-5 **Unimplemented:** Read as ‘0’

bit 4-0 **FSA<4:0>:** FIFO Area Starts with Buffer bits

11111 = Read Buffer RB31
11110 = Read Buffer RB30
•
•
•
00001 = TX/RX Buffer TRB1
00000 = TX/RX Buffer TRB0

REGISTER 21-8: CxEC: ECANx TRANSMIT/RECEIVE ERROR COUNT REGISTER

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
TERRCNT<7:0>							
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
RERRCNT<7:0>							
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **TERRCNT<7:0>:** Transmit Error Count bits

bit 7-0 **RERRCNT<7:0>:** Receive Error Count bits

REGISTER 21-9: CxCFG1: ECANx BAUD RATE CONFIGURATION REGISTER 1

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SJW1	SJW0	BRP5	BRP4	BRP3	BRP2	BRP1	BRP0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-6 **SJW<1:0>:** Synchronization Jump Width bits
`11` = Length is 4 x T_Q
`10` = Length is 3 x T_Q
`01` = Length is 2 x T_Q
`00` = Length is 1 x T_Q

bit 5-0 **BRP<5:0>:** Baud Rate Prescaler bits
`11 1111` = T_Q = 2 x 64 x 1/F_{CAN}
•
•
•
`00 0010` = T_Q = 2 x 3 x 1/F_{CAN}
`00 0001` = T_Q = 2 x 2 x 1/F_{CAN}
`00 0000` = T_Q = 2 x 1 x 1/F_{CAN}

REGISTER 23-2: AD1CON2: ADC1 CONTROL REGISTER 2 (CONTINUED)

bit 1 **BUFM:** Buffer Fill Mode Select bit

1 = Starts the buffer filling the first half of the buffer on the first interrupt and the second half of the buffer on next interrupt

0 = Always starts filling the buffer from the start address.

bit 0 **ALTS:** Alternate Input Sample Mode Select bit

1 = Uses channel input selects for Sample MUXA on first sample and Sample MUXB on next sample

0 = Always uses channel input selects for Sample MUXA

REGISTER 23-3: AD1CON3: ADC1 CONTROL REGISTER 3

R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADRC	—	—	SAMC4(1)	SAMC3(1)	SAMC2(1)	SAMC1(1)	SAMC0(1)
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADCS7(2)	ADCS6(2)	ADCS5(2)	ADCS4(2)	ADCS3(2)	ADCS2(2)	ADCS1(2)	ADCS0(2)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **ADRC:** ADC1 Conversion Clock Source bit
1 = ADC internal RC clock
0 = Clock derived from system clock

bit 14-13 **Unimplemented:** Read as ‘0’

bit 12-8 **SAMC<4:0>:** Auto-Sample Time bits(1)
11111 = 31 TAD
•
•
•
00001 = 1 TAD
00000 = 0 TAD

bit 7-0 **ADCS<7:0>:** ADC1 Conversion Clock Select bits(2)
11111111 = TP • (ADCS<7:0> + 1) = TP •256 = TAD
•
•
•
00000010 = TP • (ADCS<7:0> + 1) = TP •3 = TAD
00000001 = TP • (ADCS<7:0> + 1) = TP •2 = TAD
00000000 = TP • (ADCS<7:0> + 1) = TP •1 = TAD

Note 1: This bit is only used if SSRC<2:0> (AD1CON1<7:5>) = 111 and SSRCG (AD1CON1<4>) = 0.
2: This bit is not used if ADRC (AD1CON3<15>) = 1.

25.0 OP AMP/COMPARATOR MODULE

Note 1:	This data sheet summarizes the features of the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X families of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **“Op Amp/Comparator”** (DS70357) in the “*dsPIC33/PIC24 Family Reference Manual*”, which is available from the Microchip web site (www.microchip.com).
2:	Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 “Memory Organization”** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices contain up to four comparators, which can be configured in various ways. Comparators, CMP1, CMP2 and CMP3, also have the option to be configured as op amps, with the output being brought to an external pin for gain/filtering connections. As shown in Figure 25-1, individual comparator options are specified by the comparator module’s Special Function Register (SFR) control bits.

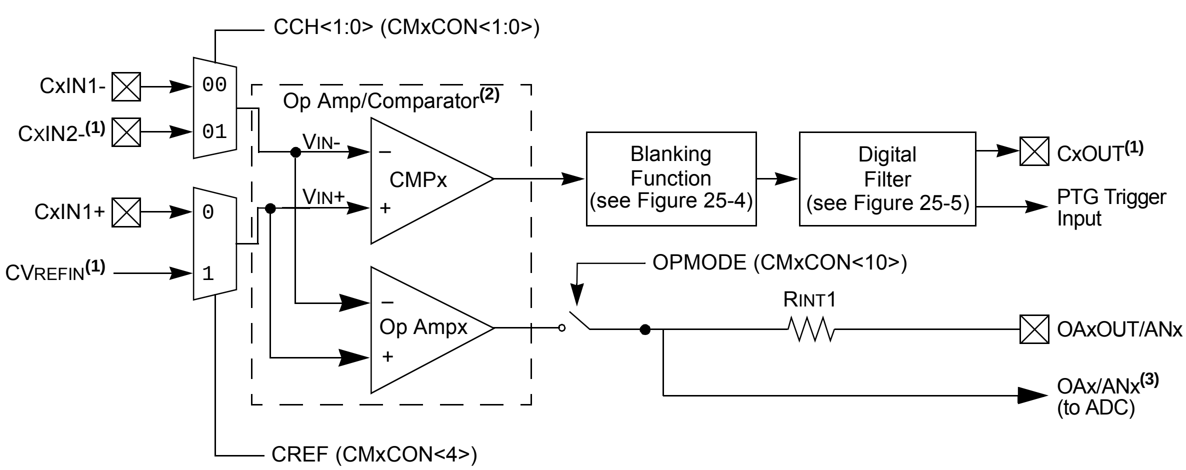
Note:	Op Amp/Comparator 3 is not available on the dsPIC33EPXXXGP502/MC502/MC202 and PIC24EP256GP/MC202 (28-pin) devices.

These options allow users to:

- Select the edge for trigger and interrupt generation
- Configure the comparator voltage reference
- Configure output blanking and masking
- Configure as a comparator or op amp (CMP1, CMP2 and CMP3 only)

Note:	Not all op amp/comparator input/output connections are available on all devices. See the **“Pin Diagrams”** section for available connections.

FIGURE 25-1: OP AMP/COMPARATOR x MODULE BLOCK DIAGRAM (MODULES 1, 2 AND 3)



Note 1: This input/output is not available as a selection when configured as an op amp (OPMODE (CMxCON<10>) = 1).
2: This module can be configured either as an op amp or a comparator using the OPMODE bit.
3: When configured as an op amp (OPMODE = 1), the ADC samples the op amp output; otherwise, the ADC samples the ANx pin.

REGISTER 25-3: CM4CON: COMPARATOR 4 CONTROL REGISTER

R/W-0	R/W-0	R/W-0	U-0	U-0	U-0	R/W-0	R/W-0
CON	COE	CPOL	—	—	—	CEVT	COUT
bit 15							bit 8

R/W-0	R/W-0	U-0	R/W-0	U-0	U-0	R/W-0	R/W-0
EVPOL1	EVPOL0	—	CREF(1)	—	—	CCH1(1)	CCH0(1)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **CON:** Comparator Enable bit
1 = Comparator is enabled
0 = Comparator is disabled

bit 14 **COE:** Comparator Output Enable bit
1 = Comparator output is present on the CxOUT pin
0 = Comparator output is internal only

bit 13 **CPOL:** Comparator Output Polarity Select bit
1 = Comparator output is inverted
0 = Comparator output is not inverted

bit 12-10 **Unimplemented:** Read as ‘0’

bit 9 **CEVT:** Comparator Event bit
1 = Comparator event according to EVPOL<1:0> settings occurred; disables future triggers and interrupts until the bit is cleared
0 = Comparator event did not occur

bit 8 **COUT:** Comparator Output bit
When CPOL = 0 (non-inverted polarity):
1 = VIN+ > VIN-
0 = VIN+ < VIN-
When CPOL = 1 (inverted polarity):
1 = VIN+ < VIN-
0 = VIN+ > VIN-

bit 7-6 **EVPOL<1:0>:** Trigger/Event/Interrupt Polarity Select bits
11 = Trigger/event/interrupt generated on any change of the comparator output (while CEVT = 0)
10 = Trigger/event/interrupt generated only on high-to-low transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
Low-to-high transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
High-to-low transition of the comparator output.
01 = Trigger/event/interrupt generated only on low-to-high transition of the polarity selected comparator output (while CEVT = 0)
If CPOL = 1 (inverted polarity):
High-to-low transition of the comparator output.
If CPOL = 0 (non-inverted polarity):
Low-to-high transition of the comparator output.
00 = Trigger/event/interrupt generation is disabled

Note 1: Inputs that are selected and not available will be tied to VSS. See the **“Pin Diagrams”** section for available inputs for each package.

REGISTER 27-1: DEVID: DEVICE ID REGISTER

R	R	R	R	R	R	R	R
DEVID<23:16>(1)							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVID<15:8>(1)							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVID<7:0>(1)							
bit 7							bit 0

Legend: R = Read-Only bit	U = Unimplemented bit

bit 23-0 **DEVID<23:0>:** Device Identifier bits(1)

Note 1: Refer to the *“dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits”* (DS70663) for the list of device ID values.

REGISTER 27-2: DEVREV: DEVICE REVISION REGISTER

R	R	R	R	R	R	R	R
DEVREV<23:16>(1)							
bit 23							bit 16

R	R	R	R	R	R	R	R
DEVREV<15:8>(1)							
bit 15							bit 8

R	R	R	R	R	R	R	R
DEVREV<7:0>(1)							
bit 7							bit 0

Legend: R = Read-only bit	U = Unimplemented bit

bit 23-0 **DEVREV<23:0>:** Device Revision bits(1)

Note 1: Refer to the *“dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits”* (DS70663) for the list of device revision values.

27.6 JTAG Interface

dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices implement a JTAG interface, which supports boundary scan device testing. Detailed information on this interface is provided in future revisions of the document.

Note:	Refer to **"Programming and Diagnostics"** (DS70608) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of the JTAG interface.

27.7 In-Circuit Serial Programming

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X devices can be serially programmed while in the end application circuit. This is done with two lines for clock and data, and three other lines for power, ground and the programming sequence. Serial programming allows customers to manufacture boards with unprogrammed devices and then program the device just before shipping the product. Serial programming also allows the most recent firmware or a custom firmware to be programmed. Refer to the *"dsPIC33E/PIC24E Flash Programming Specification for Devices with Volatile Configuration Bits"* (DS70663) for details about In-Circuit Serial Programming (ICSP).

Any of the three pairs of programming clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

27.8 In-Circuit Debugger

When MPLAB® ICD 3 or REAL ICE™ is selected as a debugger, the in-circuit debugging functionality is enabled. This function allows simple debugging functions when used with MPLAB IDE. Debugging functionality is controlled through the PGECx (Emulation/Debug Clock) and PGEDx (Emulation/Debug Data) pin functions.

Any of the three pairs of debugging clock/data pins can be used:

- PGEC1 and PGED1
- PGEC2 and PGED2
- PGEC3 and PGED3

To use the in-circuit debugger function of the device, the design must implement ICSP connections to $\overline{\text{MCLR}}$, VDD, VSS and the PGECx/PGEDx pin pair. In addition, when the feature is enabled, some of the resources are not available for general use. These resources include the first 80 bytes of data RAM and two I/O pins (PGECx and PGEDx).

27.9 Code Protection and CodeGuard™ Security

The dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X, and PIC24EPXXXGP/MC20X devices offer basic implementation of CodeGuard Security that supports only General Segment (GS) security. This feature helps protect individual Intellectual Property.

Note:	Refer to **"CodeGuard™ Security"** (DS70634) in the *"dsPIC33/PIC24 Family Reference Manual"* for further information on usage, configuration and operation of CodeGuard Security.

30.0 ELECTRICAL CHARACTERISTICS

This section provides an overview of dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X electrical characteristics. Additional information will be provided in future revisions of this document as it becomes available.

Absolute maximum ratings for the dsPIC33EPXXXGP50X, dsPIC33EPXXXMC20X/50X and PIC24EPXXXGP/MC20X family are listed below. Exposure to these maximum rating conditions for extended periods may affect device reliability. Functional operation of the device at these or any other conditions above the parameters indicated in the operation listings of this specification is not implied.

Absolute Maximum Ratings(1)

Ambient temperature under bias .... -40°C to +125°C
Storage temperature .... -65°C to +150°C
Voltage on VDD with respect to VSS .... -0.3V to +4.0V
Voltage on any pin that is not 5V tolerant, with respect to VSS(3) .... -0.3V to (VDD + 0.3V)
Voltage on any 5V tolerant pin with respect to VSS when VDD ≥ 3.0V(3) .... -0.3V to +5.5V
Voltage on any 5V tolerant pin with respect to Vss when VDD < 3.0V(3) .... -0.3V to +3.6V
Maximum current out of VSS pin .... 300 mA
Maximum current into VDD pin(2) .... 300 mA
Maximum current sunk/sourced by any 4x I/O pin .... 15 mA
Maximum current sunk/sourced by any 8x I/O pin .... 25 mA
Maximum current sunk by all ports(2,4) .... 200 mA

Note 1: Stresses above those listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only, and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

2: Maximum allowable current is a function of device maximum power dissipation (see Table 30-2).

3: See the **“Pin Diagrams”** section for the 5V tolerant pins.

4: Exceptions are: dsPIC33EPXXXGP502, dsPIC33EPXXXMC202/502 and PIC24EPXXXGP/MC202 devices, which have a maximum sink/source capability of 130 mA.

FIGURE 30-34: ECANx MODULE I/O TIMING CHARACTERISTICS

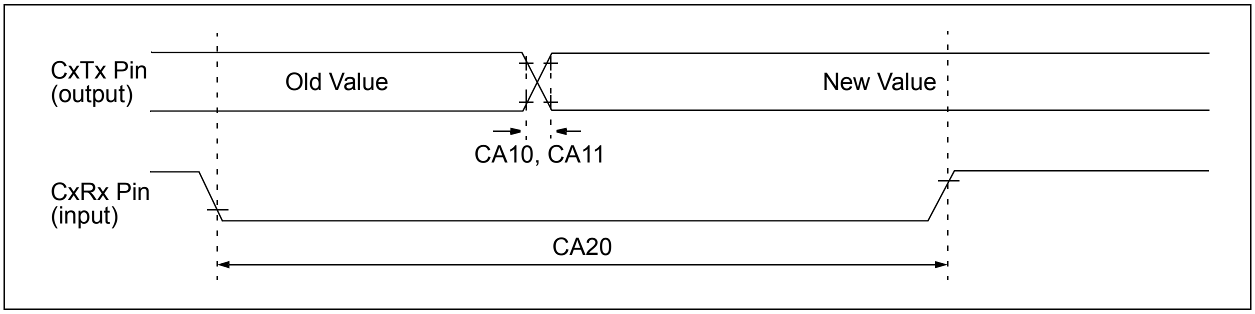


TABLE 30-51: ECANx MODULE I/O TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
CA10	TIOF	Port Output Fall Time	—	—	—	ns	See Parameter DO32
CA11	TIOR	Port Output Rise Time	—	—	—	ns	See Parameter DO31
CA20	TCWF	Pulse Width to Trigger CAN Wake-up Filter	120	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 30-35: UARTx MODULE I/O TIMING CHARACTERISTICS

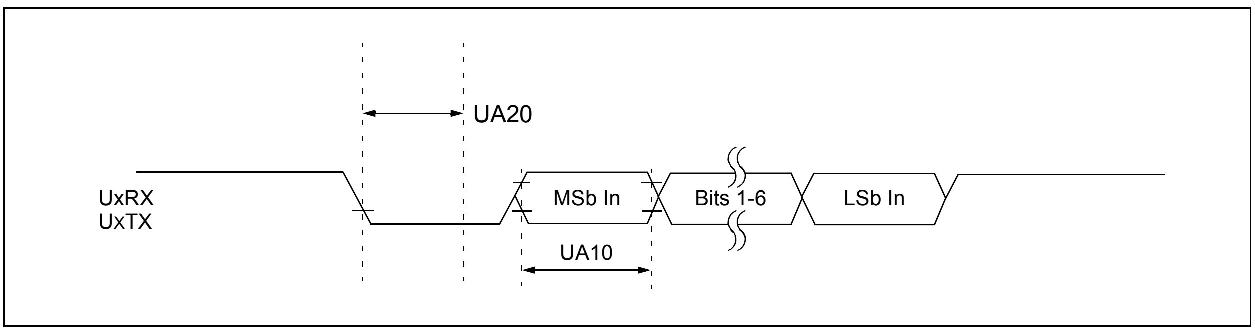


TABLE 30-52: UARTx MODULE I/O TIMING REQUIREMENTS

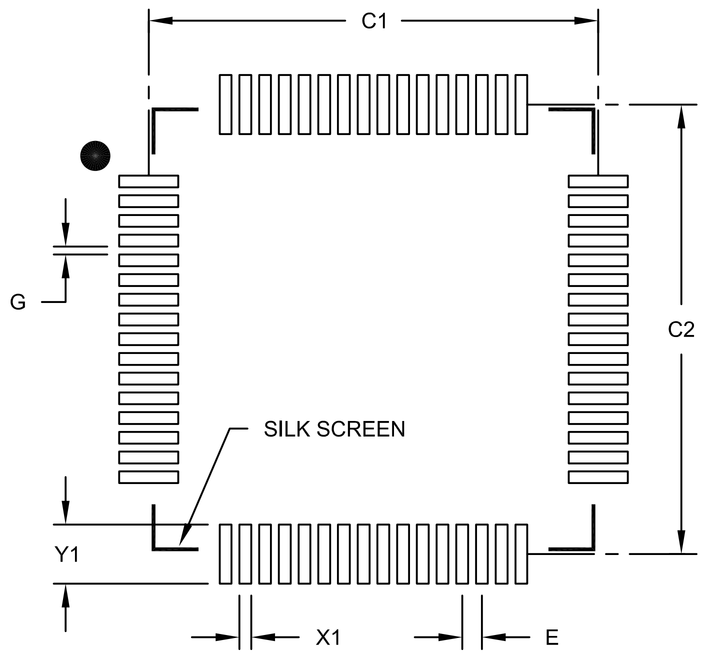
AC CHARACTERISTICS			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +125°C				
Param No.	**Symbol**	**Characteristic(1)**	**Min.**	**Typ.(2)**	**Max.**	**Units**	**Conditions**
UA10	TUABAUD	UARTx Baud Time	66.67	—	—	ns	
UA11	FBAUD	UARTx Baud Frequency	—	—	15	Mbps	
UA20	TCWF	Start Bit Pulse Width to Trigger UARTx Wake-up	500	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.50 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

TABLE A-5: MAJOR SECTION UPDATES (CONTINUED)

Section Name	Update Description
Section 30.0 "Electrical Characteristics"	• Throughout: qualifies all footnotes relating to the operation of analog modules below V_{DDMIN} (replaces "will have" with "may have") • Throughout: changes all references of SPI timing parameter symbol "TscP" to "FscP" • Table 30-1: changes V_{DD} range to 3.0V to 3.6V • Table 30-4: removes Parameter DC12 (RAM Retention Voltage) • Table 30-7: updates Maximum values at 10 and 20 MIPS • Table 30-8: adds Maximum I_{PD} values, and removes all ΔI_{WDT} entries • Adds new Table 30-9 (Watchdog Timer Delta Current) with consolidated values removed from Table 30-8. All subsequent tables are renumbered accordingly. • Table 30-10: adds footnote for all parameters for 1:2 Doze ratio • Table 30-11: - changes Minimum and Maximum values for D120 and D130 - adds Minimum and Maximum values for D131 - adds Minimum and Maximum values for D150 through D156, and removes Typical values • Table 30-12: - reformats table for readability - changes I_{OL} conditions for DO10 • Table 30-14: adds footnote to D135 • Table 30-17: changes Minimum and Maximum values for OS30 • Table 30-19: - splits temperature range and adds new values for F20a - reduces temperature range for F20b to extended temperatures only • Table 30-20: - splits temperature range and adds new values for F21a - reduces temperature range for F20b to extended temperatures only • Table 30-53: - adds Maximum value to CM30 - adds footnote ("Parameter characterized...") to multiple parameters • Table 30-55: adds Minimum and Maximum values for all CTMUI specifications, and removes Typical values • Table 30-57: adds new footnote to AD09 • Table 30-58: - removes all specifications for accuracy with external voltage references - removes Typical values for AD23a and AD24a - replaces Minimum and Maximum values for AD21a, AD22a, AD23a and AD24a with new values, split by Industrial and Extended temperatures - removes Maximum value of AD30 - removes Minimum values from AD31a and AD32a - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-59: - removes all specifications for accuracy with external voltage references - removes Maximum value of AD30 - removes Typical values for AD23b and AD24b - replaces Minimum and Maximum values for AD21b, AD22b, AD23b and AD24b with new values, split by Industrial and Extended temperatures - removes Minimum and Maximum values from AD31b, AD32b, AD33b and AD34b - adds or changes Typical values for AD30, AD31a, AD32a and AD33a • Table 30-61: Adds footnote to AD51
Section 32.0 "DC and AC Device Characteristics Graphs"	• Updates Figure 32-6 (Typical I_{DD} @ 3.3V) with individual current vs. processor speed curves for the different program memory sizes
Section 33.0 "Packaging Information"	• Replaces drawing C04-149C (64-pin QFN, 7.15 x 7.15 exposed pad) with C04-154A (64-pin QFN, 5.4 x 5.4 exposed pad)